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S5 3 AN,PN=JP 8968984
?t s5/5/all

5/5/1 (Item 1 from file: 351)
DIALOG(R)File 351:Derwent WPI
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008457343 **Image available**
WPI Acc No: 1990-344343/199046
XRAM Acc No: C90-149307
XRPX Acc No: N90-263195

**Transfer and holding device for semiconductor wafer - comprises
heat-resistant concave body and heat-insulating means**

Patent Assignee: FUJITSU LTD (FUIT)
Number of Countries: 001 Number of Patents: 001
Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 2248039	A	19901003	JP 8968984	A	19890320	199046 B

Priority Applications (No Type Date): JP 8968984 A 19890320

Abstract (Basic): JP 2248039 A

The device comprises a heat-resistant concave main body including supporting parts for supporting a semiconductor wafer, and a heat insulating means covering an upper zone of the main body.

USE - Productivity and yield of wafers are improved. (8pp

Dwg.No.1/6)

Title Terms: TRANSFER; HOLD; DEVICE; SEMICONDUCTOR; WAFER; COMPRISE; HEAT; RESISTANCE; CONCAVE; BODY; HEAT; INSULATE

Derwent Class: L03; Q77; U11

International Patent Class (Additional): C21D-001/00; F27D-003/00;
H01L-021/22

File Segment: CPI; EPI; EngPI

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DIALOG(R)File 345:Inpadoc/Fam.& Legal Stat
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Basic Patent (No,Kind,Date): JP 2248039 A2 901003 <No. of Patents: 002>

PATENT FAMILY:

JAPAN (JP)

Patent (No,Kind,Date): JP 2248039 A2 901003
TRANSFER HOLDING TOOL FOR SEMICONDUCTOR WAFER (English)

Patent Assignee: FUJITSU LTD

Author (Inventor): HARA AKITO

Priority (No,Kind,Date): JP 8968984 A 890320

Applic (No,Kind,Date): JP 8968984 A 890320

IPC: * H01L-021/22; C21D-001/00; F27D-003/00

Derwent WPI Acc No: ; C 90-344343

JAPIO Reference No: ; 140573E000056

Language of Document: Japanese

Patent (No,Kind,Date): JP 2748325 B2 980506

Patent Assignee: FUJITSU LTD

Author (Inventor): HARA AKITO

Priority (No,Kind,Date): JP 8968984 A 890320

Applic (No,Kind,Date): JP 8968984 A 890320

IPC: * H01L-021/22; H01L-021/322

Language of Document: Japanese

5/5/3 (Item 1 from file: 347)
DIALOG(R)File 347:JAPIO

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03272539 **Image available**
TRANSFER HOLDING TOOL FOR SEMICONDUCTOR WAFER

PUB. NO.: 02-248039 [JP 2248039 A]
PUBLISHED: October 03, 1990 (19901003)
INVENTOR(s): HARA AKITO
APPLICANT(s): FUJITSU LTD [000522] (A Japanese Company or Corporation), JP
 (Japan)
APPL. NO.: 01-068984 [*JP 8968984*]
FILED: March 20, 1989 (19890320)
INTL CLASS: [5] H01L-021/22; C21D-001/00; F27D-003/00
JAPIO CLASS: 42.2 (ELECTRONICS -- Solid State Components); 12.2 (METALS --
 Metallurgy & Heat Treating); 24.2 (CHEMICAL ENGINEERING --
 Heating & Cooling)
JOURNAL: Section: E, Section No. 1015, Vol. 14, No. 573, Pg. 56,
 December 19, 1990 (19901219)

ABSTRACT

PURPOSE: To reduce the generation of a dislocation crystal defect part, which is propagated to the central part of a semiconductor wafer, as low as possible by a method wherein supporting parts for the wafer and an axis to show the crystalline orientation of the wafer are made to have no relation with each other.

CONSTITUTION: A covering heat insulating means 13 to cover the upper region of a placement main body part 11 is provided and each semiconductor wafer 14 is placed between dummy wafers 25. Moreover, the wafer 14 is placed on the main body part 11 in such a way that extension lines 11 to 15 that link the vicinity of the center of the wafer 14 with each supporting part 12a to 12e and an axis C to show the crystalline orientation of the wafer 14 do not intersect orthogonally to each other within a plane including the axial direction of the parts 12a to 12e. Owing to this, in case a transfer holding tool, on which the wafer 14 is placed, is put out from or in a hot furnace in a high-temperature atmosphere, a space, which is formed of the part 11, the means 13, the wafers 25 and the wafer 14, always fulfills an adiabatic effect and the wafer 14 can be protected from a change in a state, such as an abrupt temperature rise, an abrupt temperature drop and the like.